

CLAIMS

1. A method for gluing a circuit component (1) to a circuit substrate (2) comprising the steps of:

- a) seizing a circuit component (1) using a gripper (4);
- b) moving the gripper (4) towards the surface of the circuit substrate (2) to a target distance from the surface at which adhesive (3) applied between the circuit component (1) and the circuit substrate (2) is pressed;
- c) releasing the circuit component (1) and removing the gripper (4) from the circuit component (1);

characterized by the further steps of

- d) turning the gripper (4) around an axis (A) perpendicular to the surface of the circuit substrate (2);
- e) moving the gripper (4) into the target distance again; and
- f) removing the gripper (4) again.

2. The method of claim 1, characterized in that in step b) a counteracting force opposing the movement of the gripper (4) is detected and the target distance is reached when the force reaches a predetermined value.

3. The method of claim 2, characterized in that in step b) a local coordinate of the target distance is detected and that in step e) the gripper is moved to that same local coordinate.

4. The method according to one of the preceding claims, characterized in that the turning angle in step d) is 180°.
5. The method according to one of the preceding claims, characterized in that the adhesive (3) is metered so as to yield an adhesive layer (12) of less than 10 mm thickness, preferably approx. 5 mm thickness.
6. The method according to one of the preceding claims, characterized in that the adhesive (3) is applied in advance to the circuit substrate (2) as a regular pattern of adhesive dots (3).
7. The method of claim 6, characterized in that further individual adhesive dots (13) are applied, which are closer to a corner of the circuit component (1) than the dots of the pattern.
8. The method of claim 6 or 7, characterized in that an additional adhesive dot or a row of additional adhesive dots (14) is applied centrally in the area of the regular pattern.
9. The method of one of the preceding claims, characterized in that a gripper (4) is used which has an abutment surface (6) which abuts against at least two opposite edges (10, 11) of a surface of the circuit component (1) which faces away from the circuit substrate (2).

10. The method according to one of the preceding claims, characterized in that for seizing a circuit component (1) a suction opening of the gripper (4) is placed over a circuit component (1) to be seized and the circuit component (1) is sucked.